



Product Change Notification / JAON-08IMNP537

Date:

14-Dec-2020

Product Category:

Memory

PCN Type:

Manufacturing Change

Notification Subject:

CCB 4404 Initial Notice: Qualification of ASSH as a new assembly site for 24LC512, 24AA512 and 24FC512 device families available in 8L TSSOP package.

Affected CPNs:

[JAON-08IMNP537_Affected_CPN_12142020.pdf](#)

[JAON-08IMNP537_Affected_CPN_12142020.csv](#)

Notification Text:

PCN Status: Initial notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change: Qualification of ASSH as a new assembly site for 24LC512, 24AA512 and 24FC512 device families available in 8L TSSOP package.

Pre Change:

Assembled at ANAP using gold (Au) bond wire, 8290 die attach, G700A mold compound and C7025 lead frame material with Matte Tin (Sn) plating and Ag Spot DAP Surface Prep plating or Assembled at MMT using gold (Au) bond wire, 2200D die attach, G600V mold compound and C7025 lead frame material with Matte Tin (Sn) plating and Ag Spot DAP Surface Prep plating or Assembled at NSEB using gold (Au) bond wire, 2200D die attach, G600 mold compound and C7025 lead frame material with Matte Tin (Sn) plating and Ag Spot DAP Surface Prep plating.

Assembled at ASSH using palladium coated copper (PdCu) bond wire, EN-4900G die attach, G700LY mold compound and C7025 lead frame material with Ru-PPF plating and Ru-PPF DAP Surface Prep plating.

	Pre Change			Post Change
Assembly Site	Amkor Technology Philippine (P1/P2), INC.(ANAP)	Microchip Technology Thailand (Branch) (MMT)	UTAC Thai Limited (UTL-1) LTD. (NSEB)	ASE Advanced Semiconductor (Shanghai) Co., Ltd. (ASSH)
Wire material	Au	Au	Au	PdCu
Die attach material	8290	2200D	2200D	EN-4900G
Molding compound material	G700A	G600V	G600	G700LY
Lead frame material	C7025	C7025	C7025	C7025
Lead Plating Finish	Matte Tin	Matte Sn	Matte Sn	Ru-PPF
Lead Frame Lead Lock	No	No	No	Yes
Lead Frame DAP Surface Prep	Ag Spot	Ag Spot	Ag Spot	Ru-PPF

Change Impact:None

Change Implementation Status:In Progress

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

[illegible]

Method to Identify Change: Traceability code

Qualification Plan Please open the attachments included with this PCN labeled as PCN_#_Qual_Plan.

Revision History:December 14, 2020: Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachments:

[PCN_JAON-08IMNP537_Qual_Plan.pdf](#)

[PCN_JAON-08IMNP537_Pre and Post Change_Summary.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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